



DesignCon

TecForum Sponsor Agreement



www.designcon.com

Sponsor Company _____ Address _____

City _____ State _____ Zip Code _____ Country _____

Sponsor Contact _____ Title _____ Phone _____ Fax _____ E-mail _____

Speaker _____ Title _____ Phone _____ Fax _____ E-mail _____

Program Deliverables

- 10' x 10', 10' x 20', or 20' x 20' exhibition space
- 3-hour tutorial presentation in the conference program
- Logo recognition on DesignCon web sites and on-site signage
- Recognition in pre-event broadcast e-mail
- Special recognition in the DesignCon Official Program Guide
- Full attendance report provided to sponsor (features contact information for tutorial attendees)

Terms and Conditions

1. Sponsorship fee is \$5,500, \$8,600 or \$14,800 based on 10' x 10', 10' x 20', or 20' x 20' exhibition space, and is due within 30 days of invoice date
2. The TecForum exhibition stand portion of the sponsorship is subject to the IEC Exhibition Rules and Regulations located at the end of this document.

- Sponsorship Fee (select one):**
- \$14,800 with 20' x 20' exhibition space
 - \$8,600 with 10' x 20' exhibition space
 - \$5,500 with 10' x 10' exhibition space
 - \$2,500 for current exhibitors (no additional exhibition space)

Printed Name _____ Date _____

Title _____

Cardholder Name (Print) _____ Credit Card Number _____ Exp Date (MM/YY) _____

X

Authorized Signature (signature indicates acceptance of Terms, Conditions, Development, and Deliverables outlined in this agreement)

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